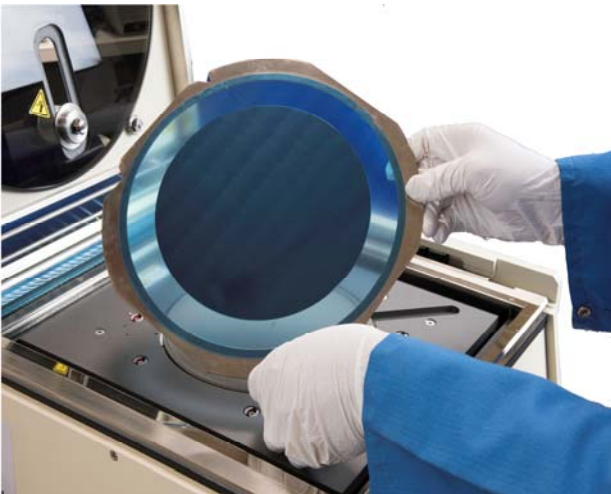




Model 3100 / 3150 / 300 Wafer / Frame Tape Applicators

Mounter Capabilities:

- Bubble-free tape application
- Safe, accurate tape trimming system
- Uniform tape tensioner
- Works with all standard film frames
- Adjustable, machine controlled roller pressure
- Closed loop temperature control
- Optional non-contact platen
- Optional static eliminator
- Optional motorized take up for tapes with liner



Specifications

Model	3100	3150	300
Wafer Size	Up to 6"	Up to 8"	12"
Weight	80 lbs	100 lbs	120 lbs
Height	11" - 21"	11" - 25"	11" - 25"
Length	28	32"	40"
Width	15" - 21"	17" - 23"	25"
Shipping Weight	95 lbs	120 lbs	180 lbs

Vacuum: 25 in/Hg • Voltage: 100-120/220 VAC
Air for (Non-Contact Option **Only**): 60 psi minimum

SEC offers a complete line of dicing and back grinding tapes.

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